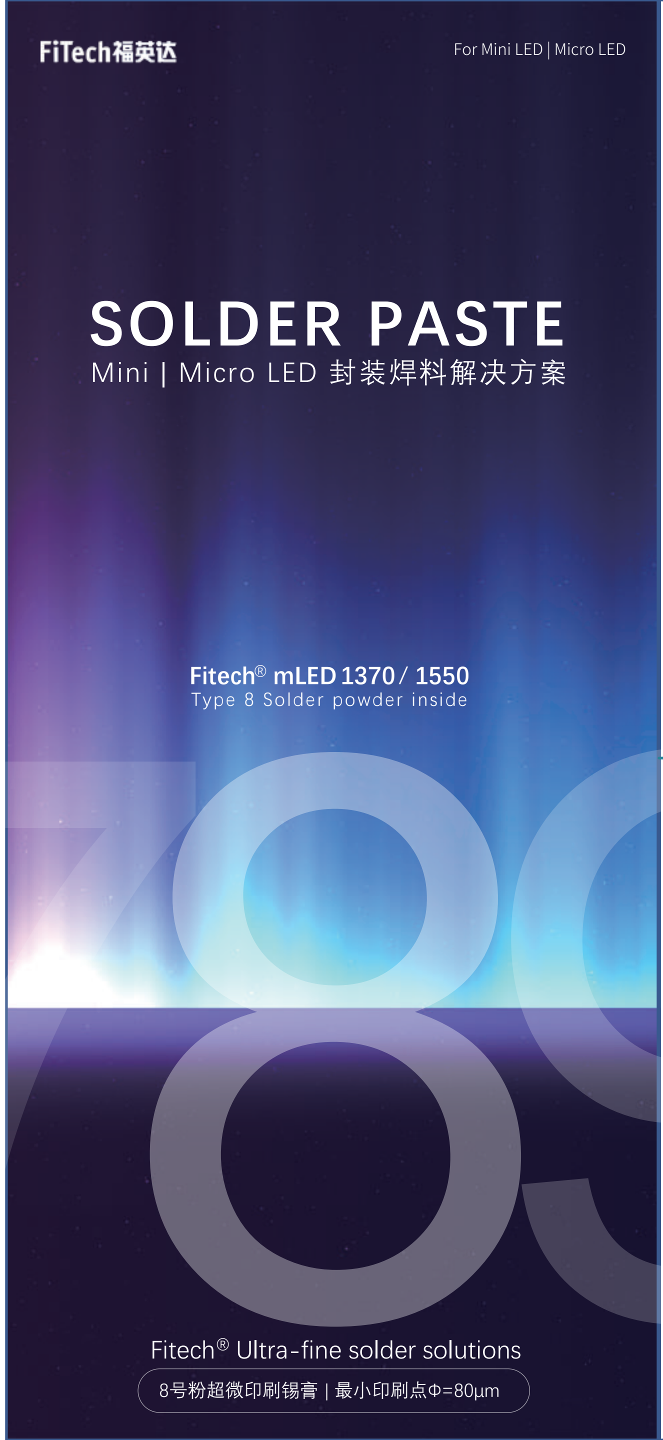
FiTech福英达

For Mini LED | Micro LED



SOLDER PASTE

Mini | Micro LED 封装焊料解决方案

Fitech® mLED 1370 / 1550

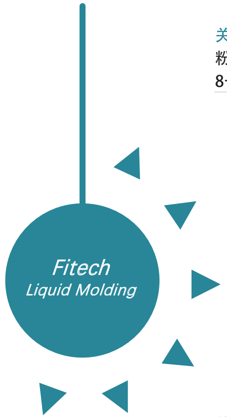
Type 8 Solder powder inside

Fitech® Ultra-fine solder solutions

8号粉超微印刷锡膏 | 最小印刷点Φ=80μm

液相成型球形合金粉末制备技术

Liquid Molding Technology



关键技术1：
粉末粒径小，可制7号粉、8号粉、9号粉及10号粉

关键技术2：
合金球大小可控，粒度分布高度集中

关键技术3：
真圆度高，可达100%①

关键技术4：
粉末表面Coating技术，保证优异的可焊性

关键技术5：
低温（熔点139℃）& 中高温（219-245℃）超微焊粉制备

[专利号：201510438826.0 / 202010800494.7]

超微焊粉粒径分布

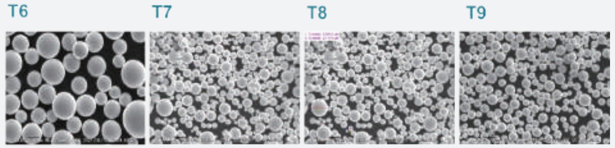
Ultra-fine Solder Powder Size Distribution

	Type 7(2-11μm)			Type 8(2-8μm)			Type 9(1-5μm)		
Size/μm	11+	11-2	2-	8+	8-2	2-	5+	5-1	1-
Fitech	≤1	≥94	≤5	≤1	≥94	≤5	≤5	≥90	≤5
JIS Z3284	≤1	≥80	≤10	≤1	≥80	≤10	Not Yet		
J-STD-005A	≤1	≥80	≤10	Not Yet			Not Yet		

深圳福英达焊粉粒径集中度远超行业标准

球形合金粉末形貌对比

Comparison of Alloy Solder Powder



Fitech's Ultra-fine Solder Powder

Competitor's Solder Powder

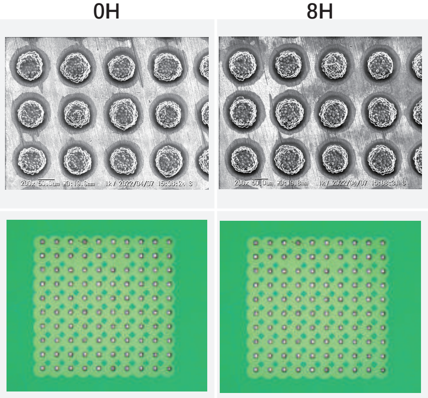
工艺稳定性-优良的工艺性能

Process Stability-Excellent Printability

Bump formulation on Φ=80um pad

Products:Fitech® mLED 1550　Photo: by SEM/Microsope

连续印刷



形状保持和稳定性，优异的脱模转印性能

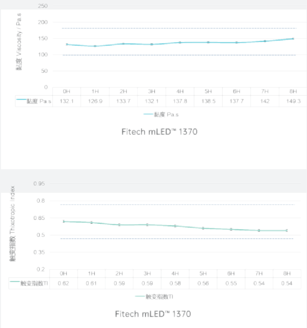
无锡珠、桥连

Fitech mLED™ 1370 低温超微无铅锡膏、 Fitech mLED™ 1550 中温超微无铅锡膏在实际应用中体现出了优异的印刷性、脱模转印性能、形状和稳定性及足量且均匀的印刷量。长时间印刷后无锡珠、桥连缺陷。

工艺稳定性-稳定的粘度和触变系数

Process Stability-Stable Viscosity and Ti

连续印刷8H Continuously print for 8H



Products:Fitech® mLED 1370

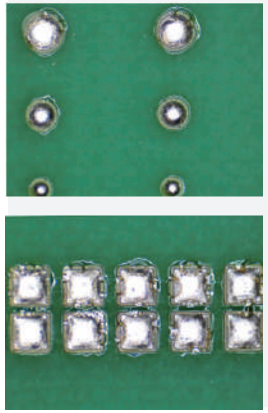
Fitech®mLED 1550

清洗-免洗/水基清洗

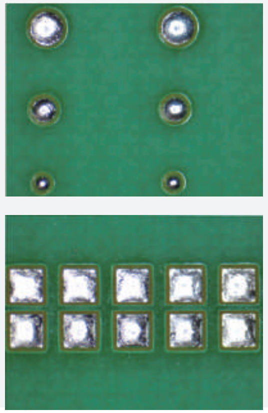
Cleanable with Water-based Agent

清洗前后外观 Appearance before and after cleaning

Composition:SAC305 Size: Type 8 (2-8μm)



清洗前



清洗后

mLED 芯片尺寸 vs 焊粉类型

mLED Chip Size vs Solder Powder Type

基于Fitech的锡膏产品 Based on Fitech’ s solder paste product

Application	Fitech Product	Alloy	Melting Point	Powder Type	Solder Point Size: Dispensing / Printing	Chip size
Mini LED	Reflow N 1700	SnBiAgX	137-145	Type 7 (11-2μm)	70/100 μm	90μm x 165μm
	Reflow N 2310	SAC305	217-219			
	Reflow N 2600	BiX	262-270			
	mLED 1370	**SnBiAg0.4**	**139**	**Type 8 (8-2μm)**	**60/80 μm**	**75μm x 145μm**
	mLED 1550	**SAC305**	**217-219**			
	FACA 1388	**SnBiAg0.4**	**139**			
	mLED 1590	SAC305	217-219	Type 9 (5-1μm)	50/70 μm	60μm x 120μm
Micro LED	FACA 1389	SnBiAg0.4	139		NA	15μm x 45μm
	Under development	SAC305	217-219	Type 10 (3-1μm)	~30 μm	35μm x 75μm
		SnBiAg	139			

Fitech mLED™ 1370/1550 可水基清洗无铅超微锡膏可提供最小**60/80μm**的锡膏点，可为最小75μmx145μm芯片提供可靠焊接效果。如需更小焊点可选用Fitech 9号锡膏

产品参数表 - Fitech mLED™ 1370/1550

Parameters of Fitech mLED™ 1370/1550

物理特性	Fitech mLED™ 1370	Fitech mLED™ 1550
合金成分	SnBiAg0.4	SAC 305
焊粉型号	Type 8	Type 8
粒径尺寸	2-8μm	2-8μm
熔点	139℃	217-219℃
助焊剂类型	水基清洗/免洗	水基清洗/免洗
卤素	无卤	无卤
工艺	印刷	印刷

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